

IN THE SPECIFICATION

Please amend the paragraph beginning at page 3, line 16 to read as follows:

^{B¹} ~~It~~ An object is to provide internal colored markings and/or indicia on packages which cannot be easily scraped off and replaced by different markings and/or indicia for purposes of relabeling or to cover up the original source of a product in cases of misappropriation of products. ~~It~~

Please amend the paragraph beginning at page 12 line 12 to read as follows:

^{B²} ~~It~~ FIG. 33 shows an alternative type of marking in accordance with this invention. In this case the difference is that the package P2 comprising a flip-chip (face down) CH3 has internal marking indicia IM formed on the bottom surface (that is the active device surface) thereof. In this case the internal marking indicia IM are protected from damage or remarking since chip CH3 is covered, at least in part, by a non-black, protection layer PL3 between elements of the BGA balls BL. Protection layer PL3 is formed directly on the lower surface (as seen in FIG. 33) of the flip-chip CH3 and on top of the internal marking indicia IM. Some chips are sensitive to light. This embodiment protects the light sensitive surface of the flip-chip CH3 from exposure to light leakage since the uncovered surface is facing the lower packaging element (not shown) which will protect the light sensitive surface of flip-chip CH3 from light. A protection layer is formed over the internal colored markings and/or indicia and the chip. The protection layer is a clear, colored, tinted and transparent or translucent encapsulating material which cannot be easily scraped off. The formation of the protection layer can be performed by molding, printing, dispensing and glob top, etc. A glob top dispenses the encapsulation material such as an epoxy material bonded to the top of IC chips during packaging thereof. ~~It~~